

Title (en)
HEAT-CONDUCTING ADHESIVE COMPOUND AND A METHOD FOR PRODUCING A HEAT-CONDUCTING ADHESIVE COMPOUND

Title (de)
WÄRMELEITENDE KLEBSTOFFVERBINDUNG UND VERFAHREN ZUM HERSTELLEN EINER WÄRMELEITENDEN KLEBSTOFFVERBINDUNG

Title (fr)
ASSEMBLAGE COLLE THERMOCONDUCTEUR, ET PROCEDE DE REALISATION D'UN ASSEMBLAGE COLLE THERMOCONDUCTEUR

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Application
EP 01907338 A 20010109

Priority
• DE 0100054 W 20010109
• DE 10009678 A 20000229

Abstract (en)
[origin: DE10009678C1] Heat conducting adhesive joint between two workpieces (1, 2) comprises a layer (3) of heat conducting material having two flat sided surfaces (31) with openings on each surface defined by hollow chambers (32) in the layer. The joint is arranged between the workpieces so that one of the surfaces contacts one of the workpieces and the other surface contacts the other workpiece. The openings are filled with adhesive (4') to join the workpieces together. An Independent claim is also included for a process for the production of a heat conducting adhesive joint between two workpieces. Preferred Features: The heat conducting material is made of silver. The heat conducting layer is made of sintered metal powder.
[origin: DE10009678C1] Heat conducting adhesive joint between two workpieces (1, 2) comprises a layer (3) of heat conducting material having two flat sided surfaces (31) with openings on each surface defined by hollow chambers (32) in the layer. The joint is arranged between the workpieces so that one of the surfaces contacts one of the workpieces and the other surface contacts the other workpiece. The openings are filled with adhesive (4') to join the workpieces together. An independent claim is also included for a process for the production of a heat conducting adhesive joint between two workpieces. Preferred Features: The heat conducting material is made of silver. The heat conducting layer is made of sintered metal powder.

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IPC 8 full level
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